

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
900V	$3.5\Omega@10V$	4A

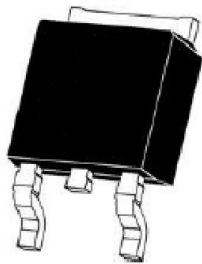
Feature

- Self-aligned planar technology
- Low conduction loss

Application

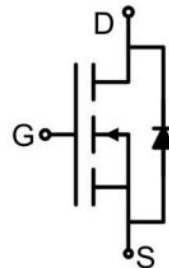
- Uninterruptible power supply (UPS)
- Power factor correction (PFC)

Package

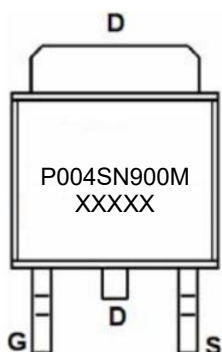


TO-252AB

Circuit diagram



Marking



Absolute maximum ratings (T_c=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V _{GS} =0V)	V _{DS}	900	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current ¹⁾ (V _{GS} =10V)	I _D	4	A
Continuous Drain Current ¹⁾ (V _{GS} =10V, T _C =100°C)	I _D	2.1	A
Pulsed Drain Current ²⁾	I _{DM}	16	A
Single Pulse Avalanche Energy ³⁾	E _{AS}	125	mJ
Power Dissipation ⁴⁾	P _D	25	W
Thermal Resistance Junction-to-Case	R _{θJC}	5	°C/W
Operating Junction Temperature	T _J	-55 ~ +150	°C
Storage Temperature Range	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	900			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =900V, V _{GS} =0V			1	μA
Gate-body leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±30V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2	3	4.5	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} =10V, I _D =2A		3	3.5	Ω
Dynamic characteristics ⁵⁾						
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f =1MHz		674		pF
Output Capacitance	C _{oss}			71		
Reverse Transfer Capacitance	C _{rss}			13		
Total Gate Charge	Q _g	V _{DS} =450V, V _{GS} =10V, I _D =4A		27		nC
Gate-Source Charge	Q _{gs}			3.5		
Gate-Drain Charge	Q _{gd}			14		
Turn-on delay time	t _{d(on)}	V _{DS} =720V, I _D =4A , R _G =25Ω		37		nS
Turn-on rise time	t _r			15		
Turn-off delay time	t _{d(off)}			144		
Turn-off fall time	t _f			36		
Source-Drain Diode characteristics						
Diode Forward Current	I _S				4	A
Diode Forward voltage	V _{SD}	V _{GS} =0V, I _S =2A			1.4	V
Reverse Recovery Time	T _{rr}	V _{GS} =0V, I _S =4A		1018		nS
Reverse Recovery Charge	Q _{rr}	di/dt =100A/μs		2.2		μC

Notes:

- 1) The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2) The test condition is Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 1%.
- 3) The EAS data shows Max. rating. L=10mH, I_{AS}=6A, V_{DD}=50V, R_G=25Ω, Starting T_J= 25°C.
- 4) The power dissipation is limited by 150°C junction temperature.
- 5) Guaranteed by design, not subject to production.

Typical Characteristics

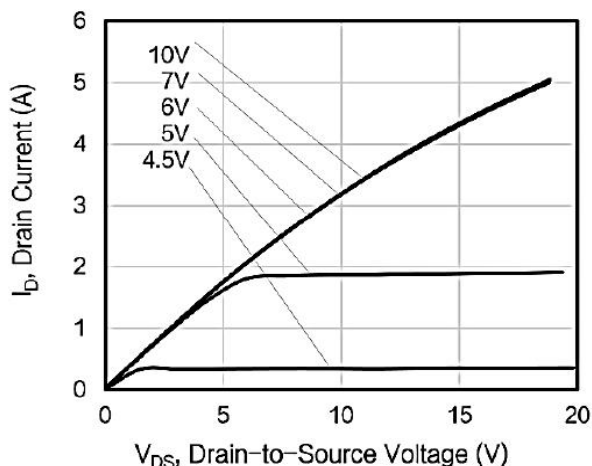


Figure 1. Output Characteristics

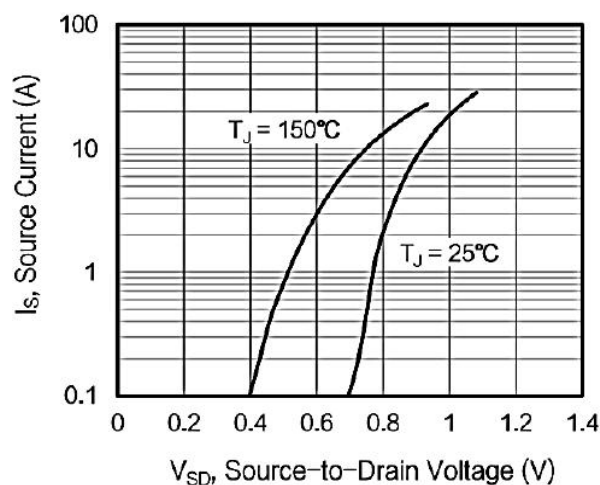


Figure 2. Body Diode Forward Voltage

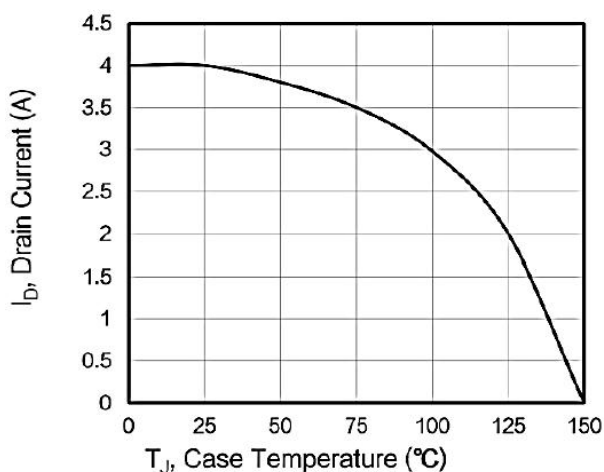


Figure3. Drain Current vs. Temperature

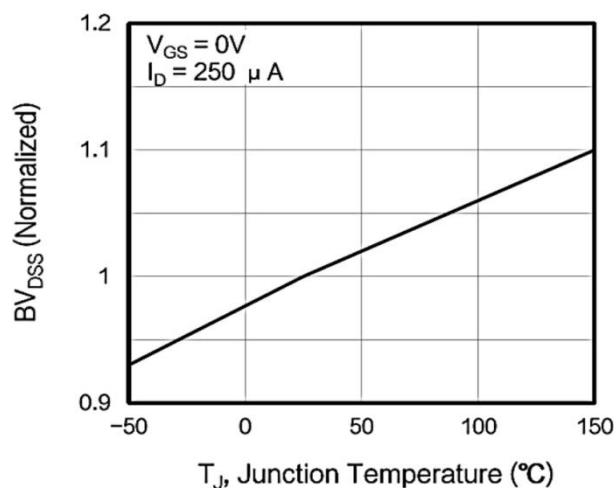


Figure4. BVDSS Variation vs. Temperature

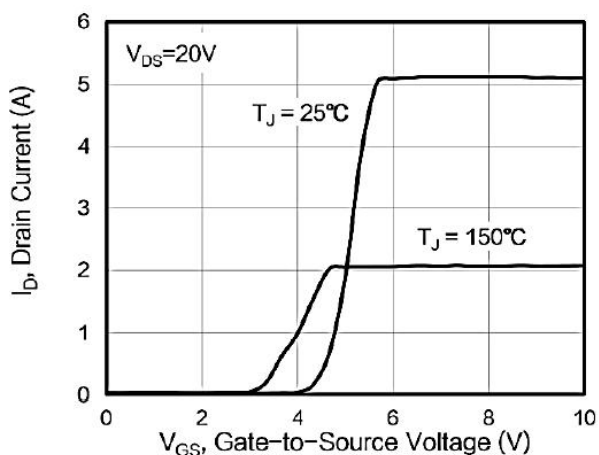


Figure 5. Transfer Characteristics

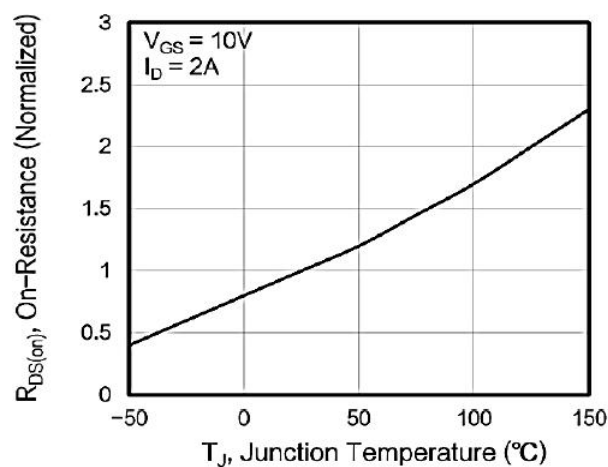


Figure 6. On-Resistance vs. Temperature

Typical Characteristics

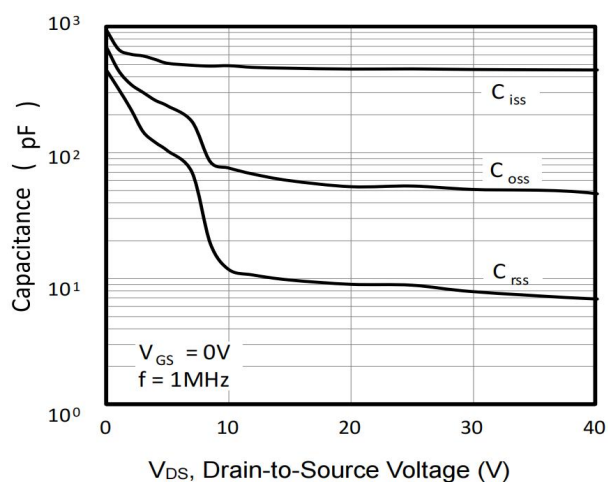


Figure 7. Capacitance

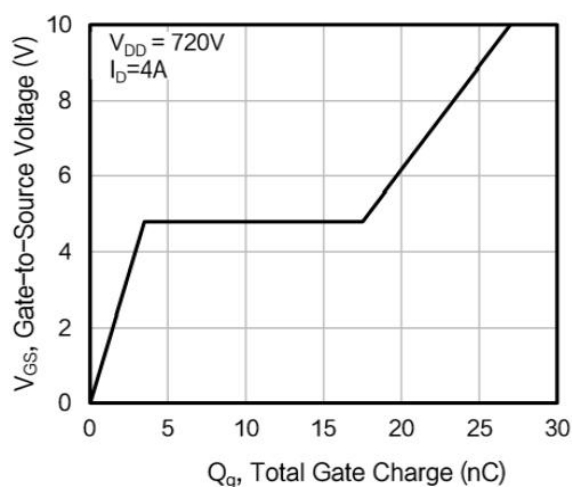


Figure 8. Gate Charge

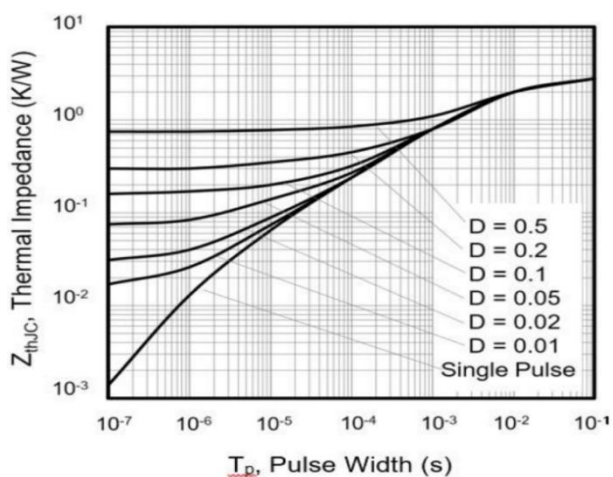
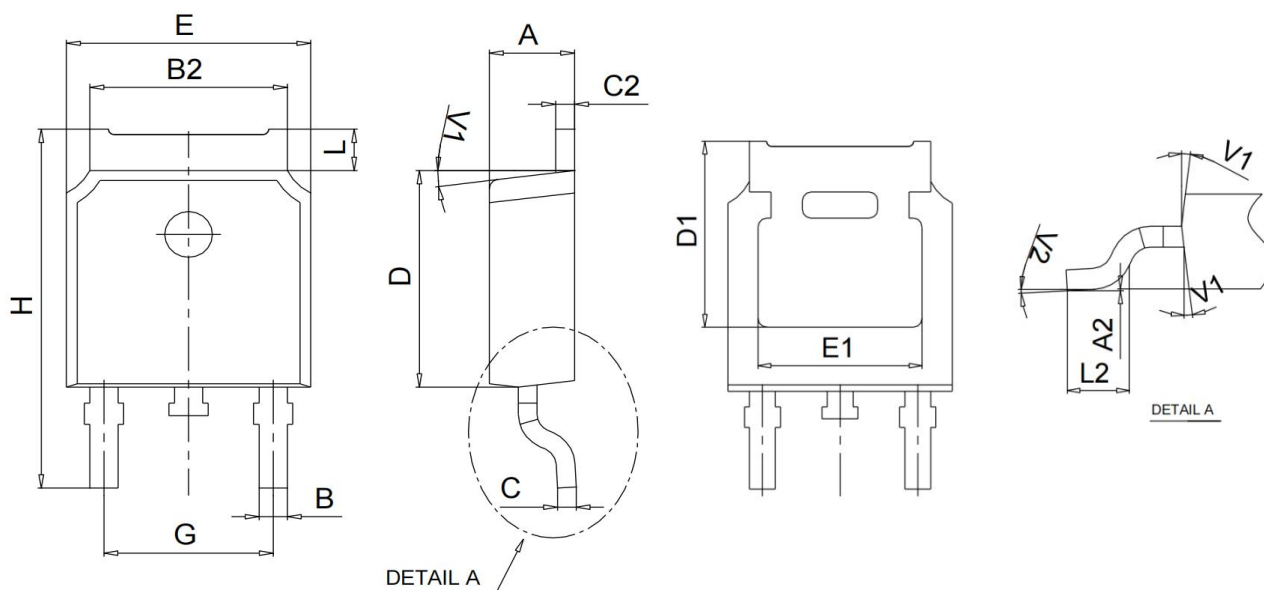


Figure 9. Transient Thermal Impedance

TO-252AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.100	2.500	0.083	0.098
A2	0.000	0.100	0.000	0.004
B	0.660	0.860	0.026	0.034
B2	5.180	5.480	0.202	0.216
C	0.400	0.600	0.016	0.024
C2	0.440	0.580	0.017	0.023
D	5.900	6.300	0.232	0.248
D1	5.300 REF.		0.209 REF.	
E	6.400	6.800	0.252	0.268
E1	4.630	-	0.182	-
G	4.470	4.670	0.176	0.184
H	9.500	10.700	0.374	0.421
L	1.090	1.210	0.043	0.048
L2	1.350	1.650	0.053	0.065
V1	7° BSC.		7° BSC.	
V2	0°	6°	0°	8°